FIG. 1A

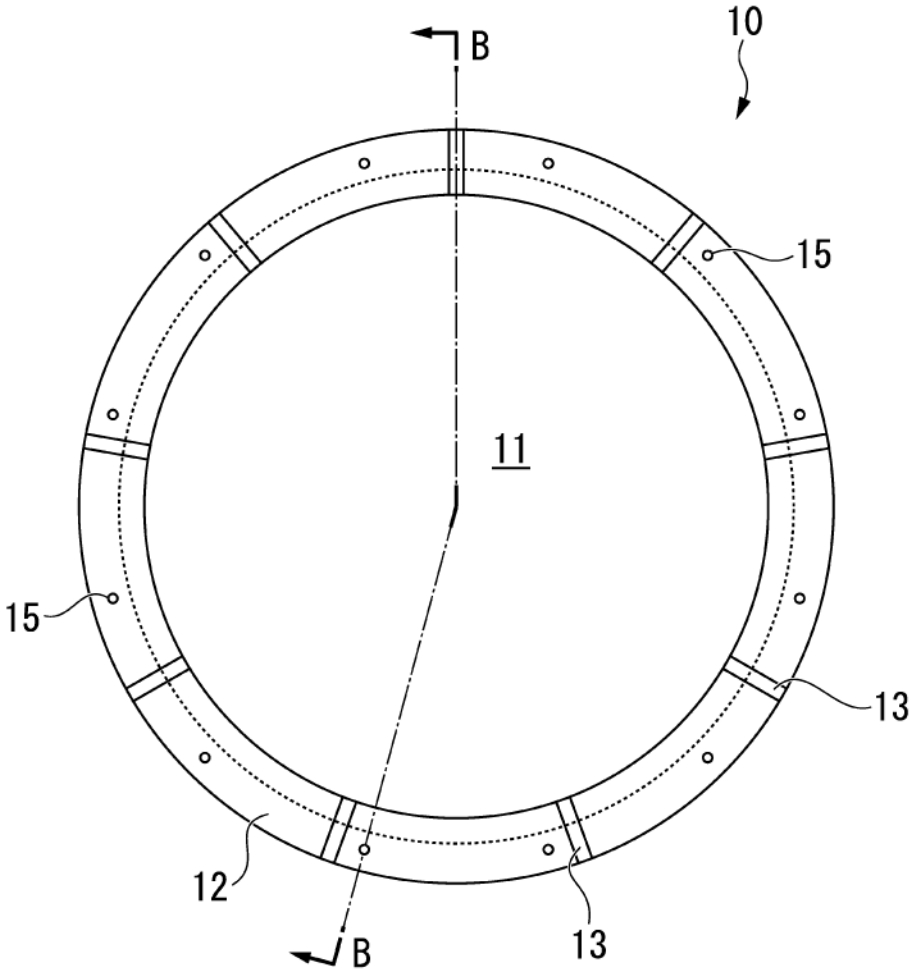


FIG. 1B

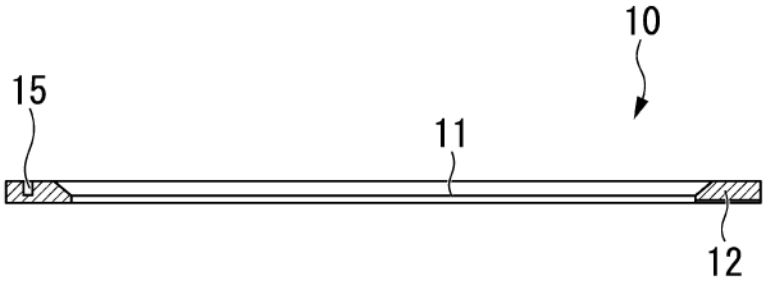


FIG. 2

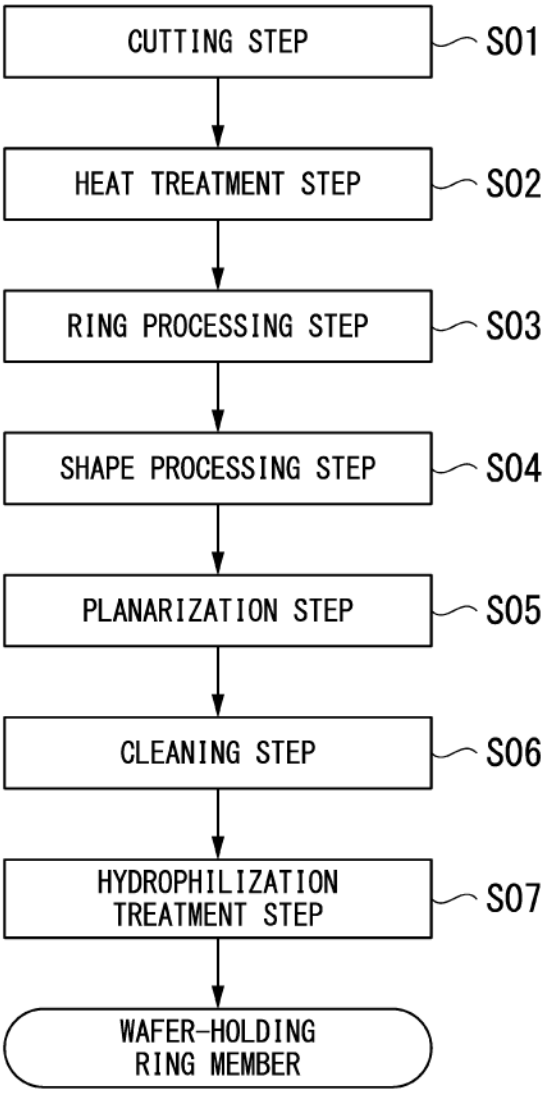

CUTTING STEP
S01
HEAT TREATMENT STEP
S02
RING PROCESSING STEP
S03
SHAPE PROCESSING STEP
S04
PLANARIZATION STEP
S05
CLEANING STEP
S06
HYDROPHILIZATION TREATMENT STEP
S07
WAFER-HOLDING RING MEMBER

FIG. 3

